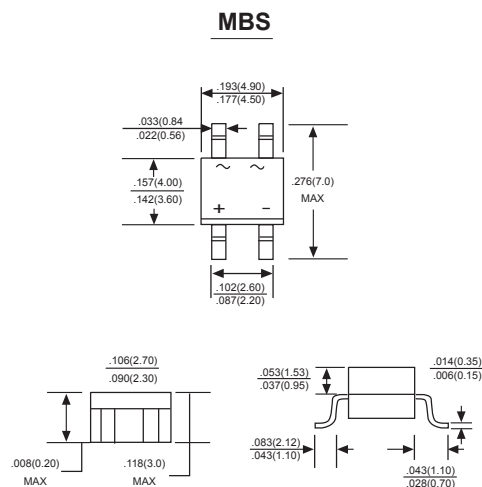


Features

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed:
260° / 10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- Leads solderable per MIL-STD-202, Method 208
- High surge current capability

Mechanical Data

- **Case:** Molded plastic body
- **Terminals:** Plated leads solderable per MIL-STD-750, Method 206
- **Polarity:** Polarity symbols marked on case
- **Mounting Position:** Any
- **Weight:** 0.04 ounce, 1.0 grams



Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	MB2S	MB4S	MB6S	MB8S	MB10S	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at T _A =30° On glass-epoxy P.C.B. On aluminum substrate	I _{F(AV)}	0.5 0.8					Amps
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	35					Amps
Maximum instantaneous forward voltage drop per leg at 0.4A	V _F	1.0					Volts
Maximum DC reverse current T _A =25° at rated DC blocking voltage T _A =100°	I _R	5.0 100					uA uA
Typical junction capacitance per leg(Note3)	C _J	15					pF
Typical thermal resistance per leg	R _{θJA}	75					°/W
Operating temperature range	T _J	-55 to +150					*
storage temperature range	T _{STG}	-55 to +150					*

NOTES: 1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads
2. On aluminum substrate P.C.B. with on area of 0.8"x0.8"(20x20mm) mounted on 0.05x0.05"(1.3x1.3mm) solder pad
3. Measured at 1.0MHz and applied reverse voltage of 4.0 volts.

